



Docket No.: M4065.0127/P127/A  
(PATENT)

#10/Response  
F. Toledo  
4/26/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Kie Y. Ahn, et al.

Application No.: 09/660,324

Group Art Unit: 2823

Confirmation No.: 2581

Filed: September 12, 2000

Examiner: F. Toledo

For: SILICON MULTI-CHIP MODULE  
PACKAGING WITH INTEGRATED  
PASSIVE COMPONENTS AND METHOD  
OF MAKING

RECEIVED  
APR 26 2002  
TC 2800 MAIL ROOM

RESPONSE TO FINAL OFFICE ACTION

Box Non-Fee Amendment  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Final Office Action dated April 1, 2002 (Paper No. 9), please reconsider the rejection in light of the following remarks.

**REMARKS/ARGUMENTS**

Claims 88, 90-95 and 96-123 are currently pending in the above-identified application, with claim 88 being the sole independent claim.

Claim 122 continues to stand rejected under 35 U.S.C. § 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains to make or use the invention (Office Action, page 2, section 1). In particular, the Office Action states, "[b]y definition alone, an